SUBSTRATE PROCESSING APPARATUS AND CLEANING METHOD FOR SUBSTRATE PROCESSING APPARATUS

Abstract

A substrate processing apparatus according to an aspect of the present disclosure includes a holding unit, a nozzle, a supply pipe, a supply valve, a drain pipe, a drain valve, and a controller. The holding unit holds and rotates a substrate. The nozzle discharges a liquid to the substrate that is held by the holding unit. The supply pipe supplies a liquid to the nozzle. The supply valve is provided on the supply pipe. The drain pipe is connected to the supply pipe on a downstream side of the supply valve and discharges a liquid inside the supply pipe. The drain valve is provided on the drain pipe. The controller controls each unit. Furthermore, the controller executes a cleaning recipe that supplies a cleaning liquid to an inside of the supply pipe and an inside of the drain pipe in a state where the supply valve and the drain valve are opened simultaneously, so that an inside of the drain pipe is cleaned.

FIG. 8